

MIL PROCESSING GROUP B TEST PLAN FOR DLZ SERIES – H2 VERSIONS (Unidirectional)

TEST	CONDITION	MIL-STD-750 TEST METHOD	SAMPLE PLAN (Units)	SMALL LOT (Units)
<u>SUBGROUP 1</u>			15 c=0	4 c=0
Solderability		2026		
Resistance to Solvents		1022		
<u>SUBGROUP 2</u>			22 c=0	6 c=0
Temp Cycle	10 cycles, 15 minutes @ min/max rated temperatures	1051		
Fine Leak	1×10^{-8} atmcc/sec	1071G/H		
Gross Leak	T _A = +125°C, no bubbles	1071D		
Electrical	Reverse Current (I _R) @ rated V _{WM} Breakdown Voltage (V _{BR}) @ I _T	4016 4022		
<u>SUBGROUP 3</u>			45 c=0	12 c=0
Electrical	Reverse Current (I _R) @ rated V _{WM} Breakdown Voltage (V _{BR}) @ I _T	4016 4022		
Pulse	20 pulses @ I _{PP} = 10A, t _p = 8 x 20µs			
Electrical	Reverse Current (I _R) @ rated V _{WM}	4016		
Steady State Op-Life (HRTB)	T _A = +125°C @ rated V _{WM} for 340 hours	1027		
Electrical	Reverse Current (I _R) @ rated V _{WM} , D-I _R = 100% or 20% of Grp A Limit, Whichever is greater Breakdown Voltage (V _{BR}) @ I _T , D-V _{BR} = ±5% from initial reading	4016 4022		
<u>SUBGROUP 4</u>				
Decap, Internal Visual	Design Verification, 1 device c=0	2075		
Bond Strength	11 wires c=0	2037		
<u>SUBGROUP 5</u>	Not Applicable			
<u>SUBGROUP 6</u>			32 c=0	12 c=0
Electrical	Reverse Current (I _R) @ rated V _{WM} Breakdown Voltage (V _{BR}) @ I _T	4016 4022		
High Temperature Life (no-op)	Tstg = +150°C for 340 hours	1032		
Electrical	Reverse Current (I _R) @ rated V _{WM} , D-I _R = 100% or 20% of Grp A Limit, Whichever is greater Breakdown Voltage (V _{BR}) @ I _T , D-V _{BR} = ±5% from initial reading	4016 4022		